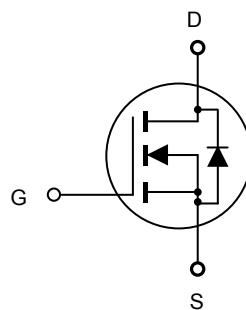


CED55A3/CEU55A3

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 25V, 38A, $R_{DS(ON)} = 14\text{m}\Omega$ @ $V_{GS} = 10\text{V}$.
 $R_{DS(ON)} = 24\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	25	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	38	A
Drain Current-Pulsed ^a	I_{DM}	152	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	P_D	31.25 0.25	W W/ $^\circ\text{C}$
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	R_{JC}	4	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	R_{JA}	50	$^\circ\text{C}/\text{W}$



CED55A3/CEU55A3

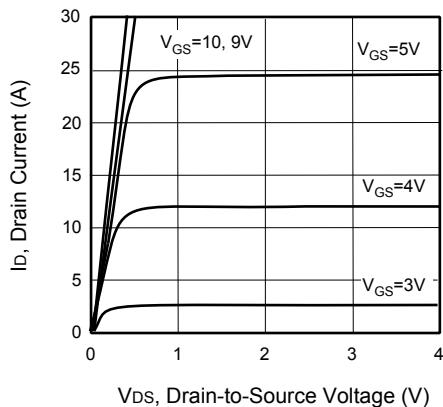
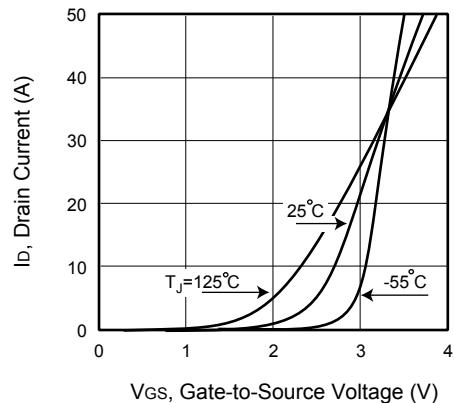
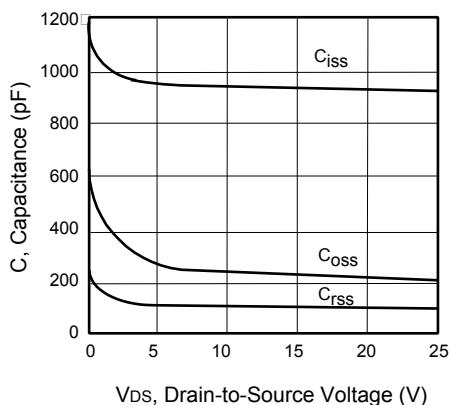
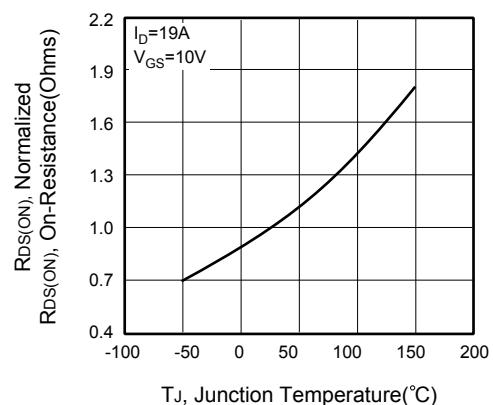
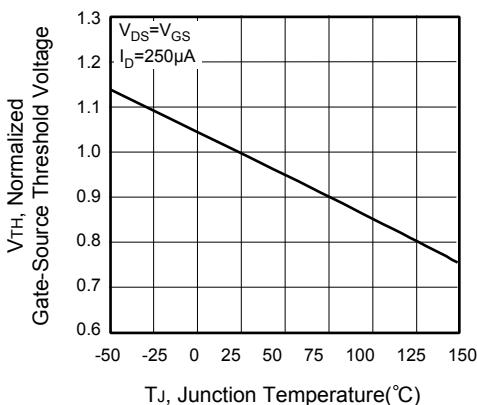
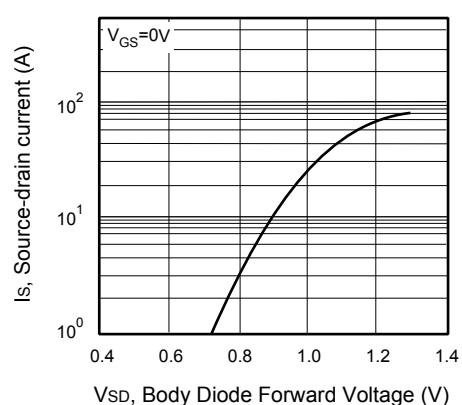
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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	25			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 19\text{A}$		10.5	14	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 15.2\text{A}$		16	24	$\text{m}\Omega$
Dynamic Characteristics^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		921		pF
Output Capacitance	C_{oss}			209		pF
Reverse Transfer Capacitance	C_{rss}			108		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 15\text{V}, I_D = 35\text{A}, \square$ $V_{\text{GS}} = 4.5\text{V}, R_{\text{GEN}} = 16\Omega$		20	40	ns
Turn-On Rise Time	t_r			6	10	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			50	100	ns
Turn-Off Fall Time	t_f			18	35	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 15\text{V}, I_D = 35\text{A},$ $V_{\text{GS}} = 10\text{V}$		16	21	nC
Gate-Source Charge	Q_{gs}			2.5		nC
Gate-Drain Charge	Q_{gd}			3.1		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				38	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 38\text{A}$			1.0	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- c.Guaranteed by design, not subject to production testing.

**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**

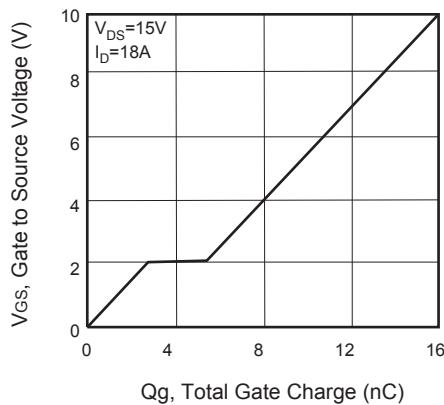


Figure 7. Gate Charge

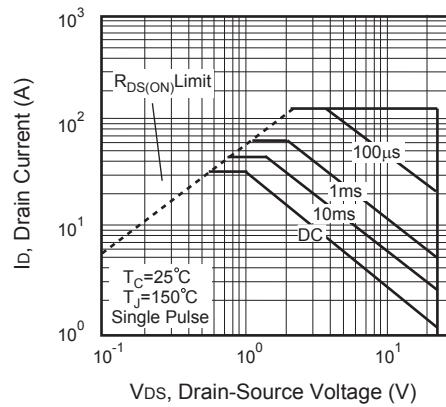


Figure 8. Maximum Safe Operating Area

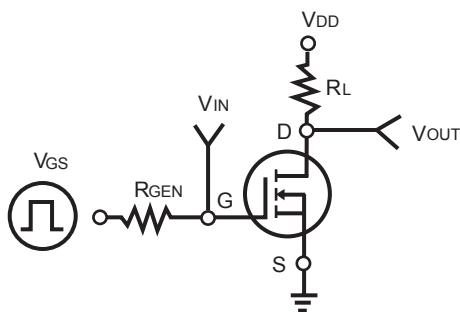


Figure 9. Switching Test Circuit



Figure 10. Switching Waveforms

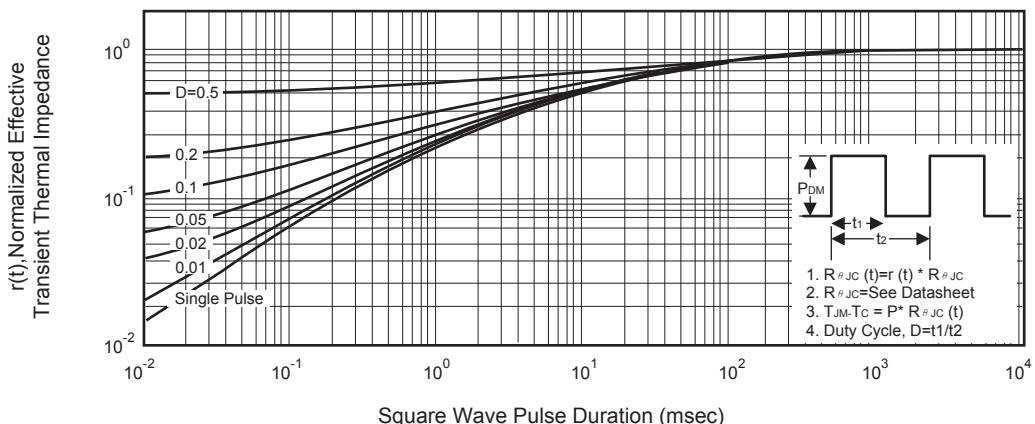


Figure 11. Normalized Thermal Transient Impedance Curve